

Claims

We claim:

1. A method for packing wafers comprising the steps of:
putting a cassette in which wafers are inserted, into a packing bag; and
5 sealing the packing bag by mechanically allowing the packing bag to be tightly adhered along an external form of the cassette, molding a border of the packing bag and cutting an unnecessary border of the packing bag.
2. The method for packing wafers according to Claim 1, wherein the
10 caliber of the wafer is 300 mm.
3. The method for packing wafers according to Claim 1, wherein the step of putting a cassette into a packing bag comprises the steps of:
sealing the cassette in a polypropylene bag; and
15 putting the cassette sealed by the polypropylene bag, into an aluminum bag.
4. The method for packing wafers according to Claim 3, wherein the step of sealing the cassette in a polypropylene bag comprises the steps of:
putting the cassette into the polypropylene bag; and
20 sealing the polypropylene bag by maintaining the polypropylene bag in a state of being loose with respect to the external form of the cassette.
5. The method for packing wafers according to Claim 3, wherein the
25 border of the aluminum bag is molded in the step of sealing the packing bag.
6. The method for packing wafers according to Claim 1, wherein a vacuum is not necessary when the packing bag is tightly adhered along the external form of the cassette, in the step of sealing the packing bag.
7. A method for packing wafers comprising the steps of:
sealing a cassette in which wafers are inserted, in a polypropylene bag;
30 putting the cassette in a state of being sealed by the polypropylene bag, into an aluminum bag; and

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sealing the aluminum bag by mechanically allowing the aluminum bag to be tightly adhered along an external form of the cassette, molding a border of the aluminum bag and cutting an unnecessary border of the aluminum bag.

5 8. The method for packing wafers according to Claim 7, wherein the caliber the wafer is 300 mm.

9. The method for packing wafers according to Claim 7, wherein the step of sealing a cassette in a polypropylene bag comprises the steps of:
10 putting the cassette into the polypropylene bag; and
 sealing the polypropylene bag by maintaining the polypropylene bag in a state of being loose with respect to the external form of the cassette.

10. The method for packing wafers according to Claim 7, wherein a
15 vacuum is not necessary when the aluminum bag is tightly adhered along the external form of the cassette, in the step of sealing the aluminum bag.

20 11. A method of packing a semiconductor wafer, comprising:
 providing a carrying device that holds the semiconductor wafer; and
 inserting the carrying device into a packing bag; and
 molding the packing bag using at least a portion of an external form of the carrying device as a guide such that a portion of the packing bag substantially conforms to the at least a portion of the external form of the carrying device.

25 12. A method as recited in Claim 11 wherein the packing bag is a second packing bag, the method further comprising:
 inserting the carrying device into a first packing bag; and
 wherein inserting the carrying device into the second packing bag comprises:
 inserting the carrying device and the first packing bag into the second packing
30 bag.

13. A method as recited in Claim 12, further comprising:

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sealing the first packing bag such that the carrying device remains in communication with the environment external to the first packing bag.

14. A method as recited in Claim 13, wherein sealing the first packing bag comprises:
- 5 folding a portion of the first packing bag through which the carrying device was inserted.

15. A method as recited in Claim 12, wherein the first packing bag is a polypropylene bag.

16. A method as recited in Claim 12, wherein the second packing bag is an aluminum bag.

17. A method as recited in Claim 12, wherein inserting the carrying device into the first packing bag, inserting the carrying device and the first packing bag into the second packing bag, and molding the second packing bag are performed in a packing room that is on a same level as a wafer cleaning room.

18. A method as recited in Claim 17, further comprising: cleaning the semiconductor wafer before inserting the carrying device into the first packing bag, inserting the carrying device and the first packing bag into the second packing bag, and molding the second packing bag.

19. A method as recited in Claim 11, further comprising: trimming a portion of the packing bag that does not substantially conform to the at least a portion of the external form of the carrying device.

20. A method as recite in Claim 11, wherein the semiconductor wafer has a 300 mm caliber.

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